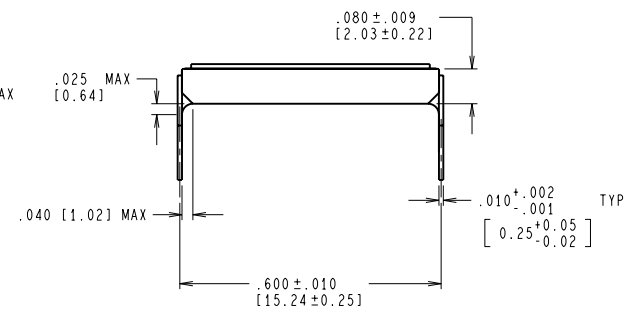
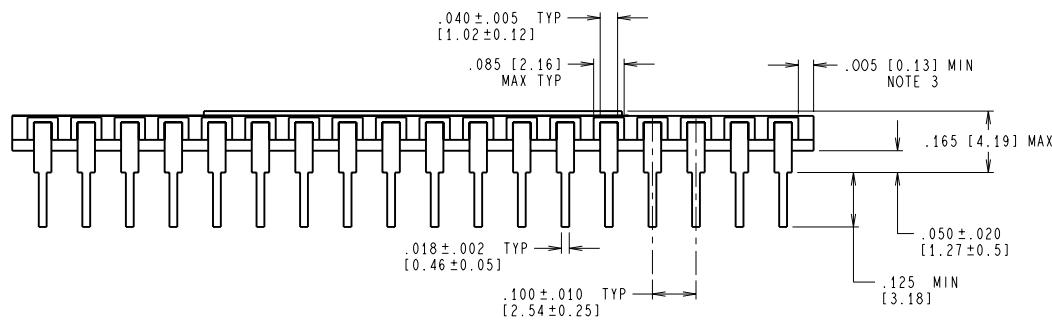
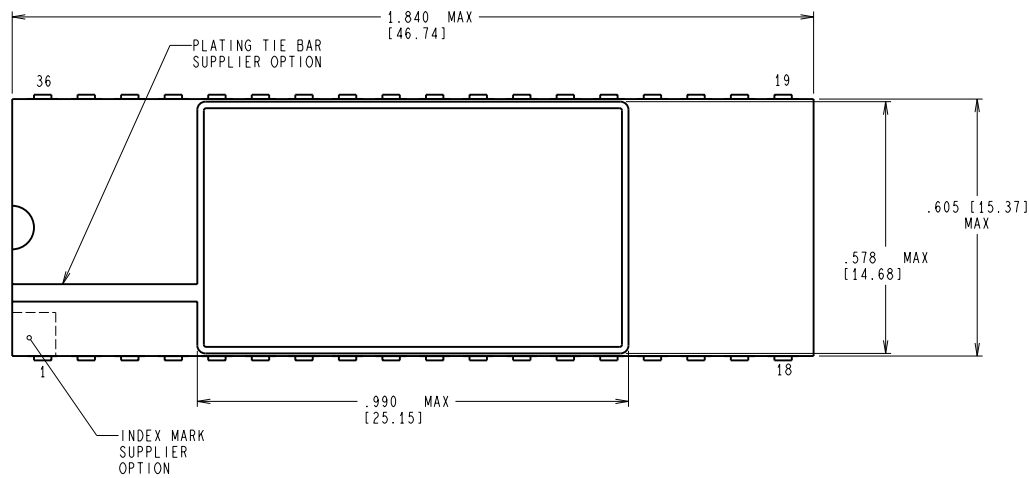




CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED.

- LEAD FINISH TO BE ONE OF THE FOLLOWING:
 - 200 MICROINCHES/5.08 MICROMETERS MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
 - 50 MICROINCHES/1.27 MICROMETERS MINIMUM GOLD OVER 50 TO 350 MICROINCHES/1.27 TO 8.89 MICROMETERS NICKEL UNDERPLATE.
- LEAD FINISH, NICKEL UNDERPLATE AND BASIS METAL SHALL CONFORM TO THE REQUIREMENTS OF MIL-PRF-38535.
- DIMENSION .005 IN/0.13mm MINIMUM SHALL BE MEASURED FROM THE EDGE OF THE FURTHEST EXTENSION OF THE METAL PAD OR LEAD.
- REFERENCE JEDEC REGISTRATION MS-015, VARIATION CD, DATED 7/90.

REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL.	10479	07/31/94	DEG/AP
B	REVISE AND REDRAW PER NEW STANDARD.	11362	02/08/96	DEG/

APPROVALS		DATE	NATIONAL SEMICONDUCTOR CORPORATION		
DRAWN	Dwayne Grady	02/08/96	2900 Semiconductor Drive, Santa Clara, CA 95052-8090		
DTG. CHK.			DIP, SIDE BRAZE, CERAMIC, 36 LEAD, .600 CTRS.		
ENGR. CHK.					
APPROVAL					
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
INCH [MM]		N/A	C	MKT-DA36A	B
DO NOT SCALE DRAWING				SHEET 1 of 1	